



LAND



SEA



AIR

7SL-KR5610

**INTEL 4/5TH XEON SP 1U SHORT DEPTH
MILITARY RUGGED HPC**



- Intel® 4th Xeon Scalable Processor CPUs with up to 32 Cores / 5th Xeon® Scalable Processor CPUs with up to 16 Cores
- 8 DDR5 DIMM slots, supports RDIMM 1 TB max, speeds up to 5600 MT/s. Supports registered ECC DDR5 DIMMs only
- Front bays: Up to 4 x 2.5-inch SATA, SAS, or NVMe SSDs max 30.72 TB
- Cryptographically signed firmware, Secure Boot, TPM 2.0 FIPS, CC-TCG certified
- 4x 25G LAN SFP+, 1x RJ45 1GbE LAN, 1x USB 3.0, 1x USB 2.0, 1x Mini-DP
- Up to 2 PCIe slots (2 x16 Gen5)
- Redundant 14000W Platinum power supply support 100V-240V, 240V HVDC support 1+1 active-active support hot plug
- Embedded Management: iDRAG Direct, iDRAC RESTful API with Redfish iDRAC Service
- Lightweight aluminum chassis with stainless steel reinforcement
- Electrical interference input filtering and cable shielding
- Conformal coating (Optional)
- Design to meet MIL-STD-461/MIL-STD-810

Product Highlight

Technical Specification

5th/4th Gen Intel® Xeon® Scalable processors, Single Socket LGA-4677 (Socket E)
Up to 16/32 Cores per Processor
Up to 1TB memory with 8 DIMM slots
Storage Internal Controllers: PERC H965i, PERC H965e, PERC H755, PERC H355, HBA355i
(BOSS-N1): HWRAID 1, 2 x M.2 NVMe SSDs

Management and Operating System

Windows®, VMWARE, Ubuntu Server LTS, Windows Server with Hyper-V, Red Hat Enterprise Linux, SUSE Linux Enterprise Server, VMware ESX
AMI UEFI BIOS type
iDRAC9, iDRAC Direct, iDRAC RESTful API with Redfish, iDRAC Service Module, NativeEdge Endpoint Orchestrator
TPM 2.0 support

Expansion

Up to 2 x PCIe 5.0 x 16 Slots
4x 2.5" Swappable SSD, support SATAIII (6Gbps)

Input/Output Versatility

1x Power Button
1x SSD Status LED
2x AC-IN Jack
(Front)
1x iDRAC Direct (Micro-AB USB 2.0) port, 1 x USB 2.0
(Rear)
1 x iDRAC dedicated port, 1 x USB 3.0, 1 x Serial (Micro- AB USB 2.0) port, 1 x Mini-DisplayPort, 1 x RJ45 for dry contact, 4 x 25 GbE SFP+ LOM

Power Supply Options

Redundant 1400 W Platinum 100/240V VAC
1100 W 48V~60V VDC (Optional)

Thermal Solution

Air Cooling 6 x Standard cold swap fans

Environmental

Operating

Temperature: -10°C to 55°C
Humidity: 5%to 95%, non-condensing
Shock: 3 axis, 25g
Vibration: 5Grms

Non-Operating

Temperature: -20°C to 60°C
Humidity: 5%to 95%, non-condensing

MIL-STD-810 Test

Method 500.5, Procedures I and II (Altitude, Operation):
12,192M, (40,000 ft) for the initial cabin altitude (18.8Kpa or 2.73 Psia)
Method 500.5, Procedures III and IV (Altitude, Non-Operation):
15,240, (50,000 ft) for the initial cabin altitude (14.9Kpa or 2.16 Psia)
Method 501.5, Procedure I (Storage/High Temperature)
Method 501.5, Procedure II (Operation/High Temperature)
Method 502.5, Procedure I (Storage/Low Temperature)
Method 502.5, Procedure II (Operation/Low Temperature)
Method 503.5, Procedure I (Temperature shock)
Method 507.5, Procedure II (Temperature & Humidity)
Method 509.7 Salt Spray (50±5)g/L(Optional for Conformal Coating)
Method 514.6, Vibration Category 24/Non-Operating (Category 20 & 24, Vibration)
Method 514.6, Vibration Category 20/Operating (Category 20 & 24, Vibration)
Method 516.6, Shock-Procedure V Non-Operating (Mechanical Shock)
Method 516.6, Shock-Procedure I Operating (Mechanical Shock)

Mechanical

Height: 42.8mm
Width: 19 inches (482.6mm)
Depth: 22 inches (566.05mm) with bezel
18.61inches (472.7mm) without bezel
Weight: 25.06 pounds (11.37kg)

Specifications

SYSTEM

Processor	5th Gen Intel® Xeon® / 4th Gen Intel® Xeon® Scalable processors, Socket E (LGA-4677)
CPU Core Count	Up to 16Cores/32Cores
Memory type	DDR5-5600MT/s RDIMM ECC, up to 1TB in 8 DIMM slot
TPM	Chipset: Infineon, Type: TPM 2.0
IPMI	iDRAC RESTful API with Redfish
BIOS	AMI UEFI BIOS
USB	1x USB3.0 +1x USB2.0 ports
Ethernet	4x 25G Ethernet SFP+ Ports
Power Type	100V~240V AC IN Redundant
Storage	4x 2.5" Swappable SATA SSD
Operating Temp.	-10°C to +55°C
Dimension	482mm(W) x 566mm(D)x42mm(H)

FRONT I/O

Power Button	1x
SSD LED indicator	1x
Swappable SSD Tray	4x
iDRAC	1x iDRAC Direct (Micro-AB USB 2.0) port, 1 x USB 2.0

REAR I/O

iDRAC	1x iDRAC dedicated Direct port
USB3.0	1x
Serial	1 x (Micro-AB USB 2.0)
1G LAN	1x
25G LAN	4x
Display port	1x Mini-DP

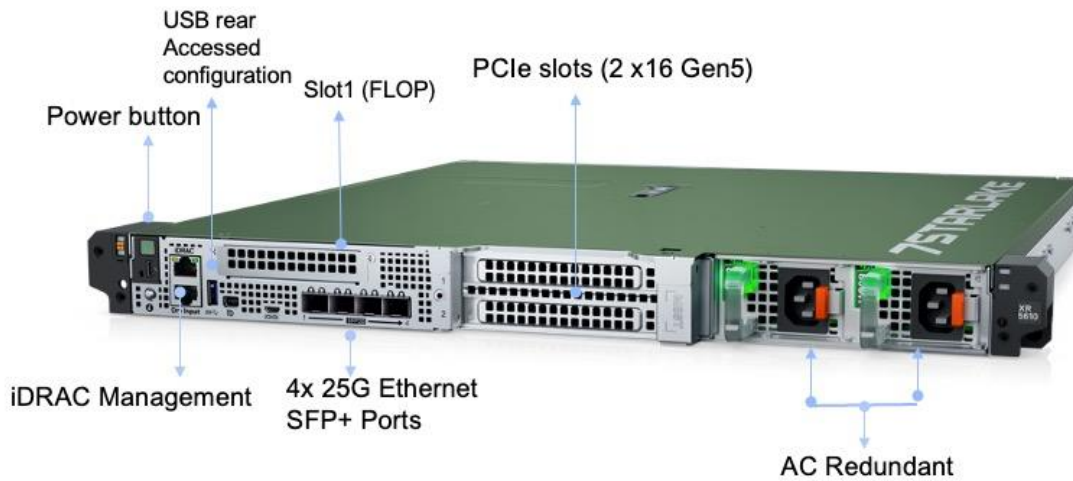
ENVIRONMENTAL

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Operating Temp	-10°C to +55°C
Storage Temp.	-20°C to +60°C
Relative Humidity	5% to 95%, non-condensing.

Appearance



Ordering Information

	7SL-XR5610-AC	7SL-XR5610-DC
CPU	5th Gen Intel® Xeon® / 4th Gen Intel® Xeon® Scalable processors, Socket E (LGA-4677)	5th Gen Intel® Xeon® / 4th Gen Intel® Xeon® Scalable processors, Socket E (LGA-4677)
RAM	DDR5-5600MT/s RDIMM ECC, up to 1TB in 8 DIMM slot	DDR5-5600MT/s RDIMM ECC, up to 1TB in 8 DIMM slot
Storage	4x 2.5" Swappable SATA SSD	4x 2.5" Swappable SATA SSD
Power	1400W 100V~240V AC IN Redundant	1100W DC 48V~60V
Thermal	Active Smart Fan Cooling	Active Smart Fan Cooling